

FIG. 1 (PRIOR ART)

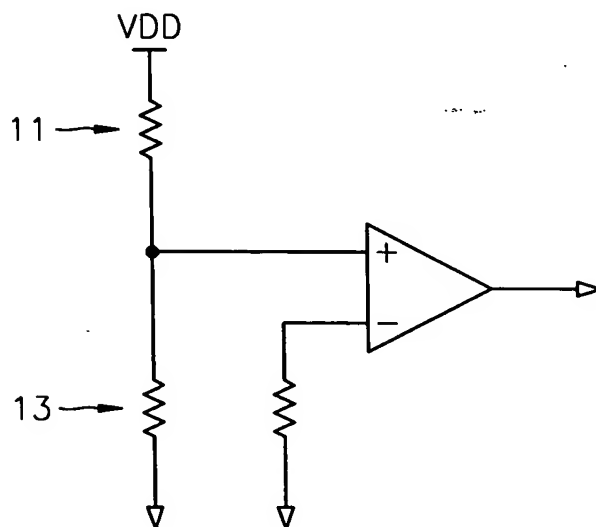


FIG. 2 (PRIOR ART)

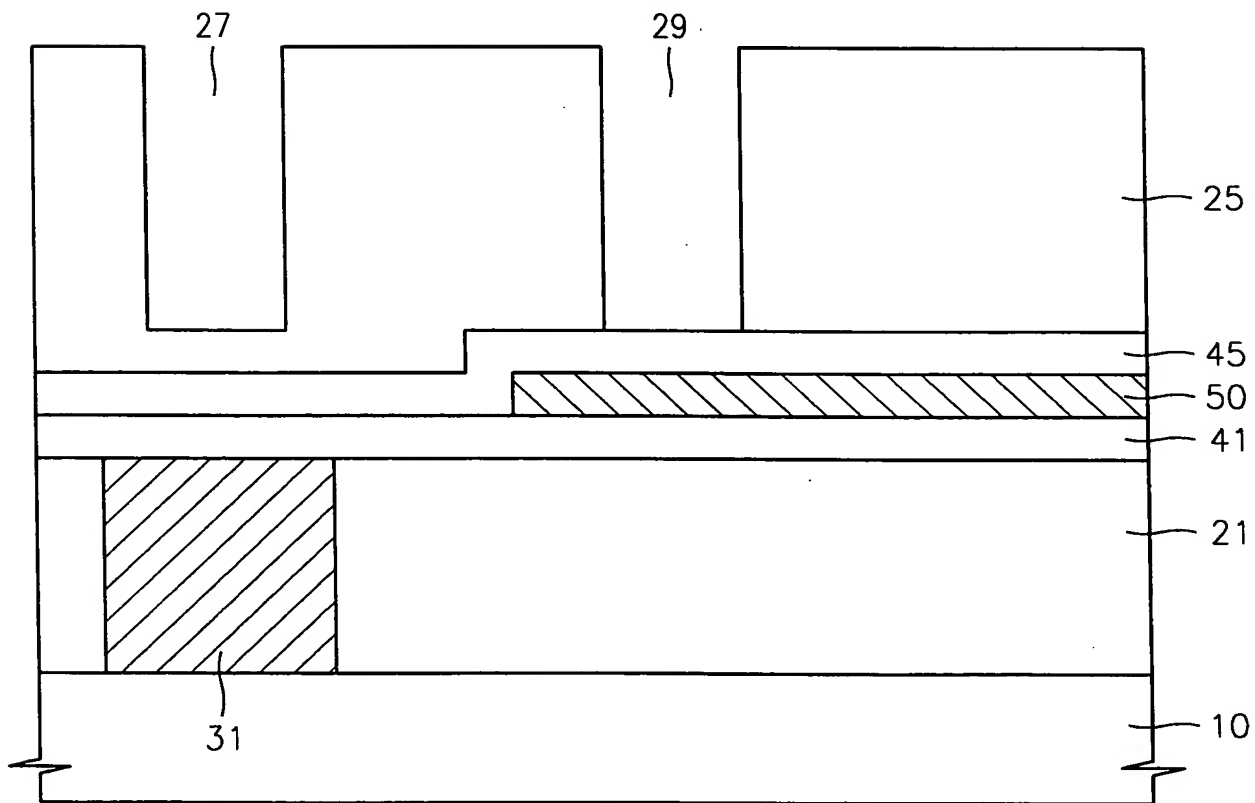


FIG. 3 (PRIOR ART)

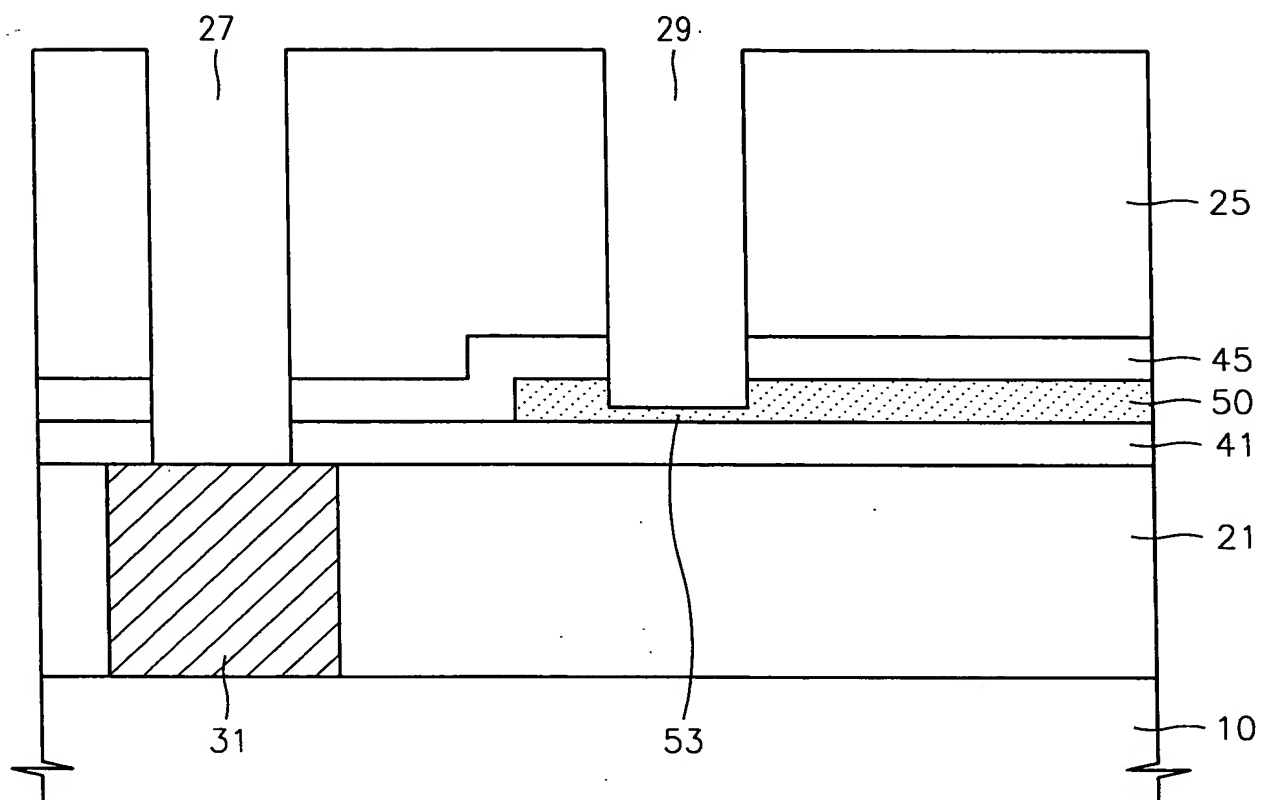


FIG. 4 (PRIOR ART)

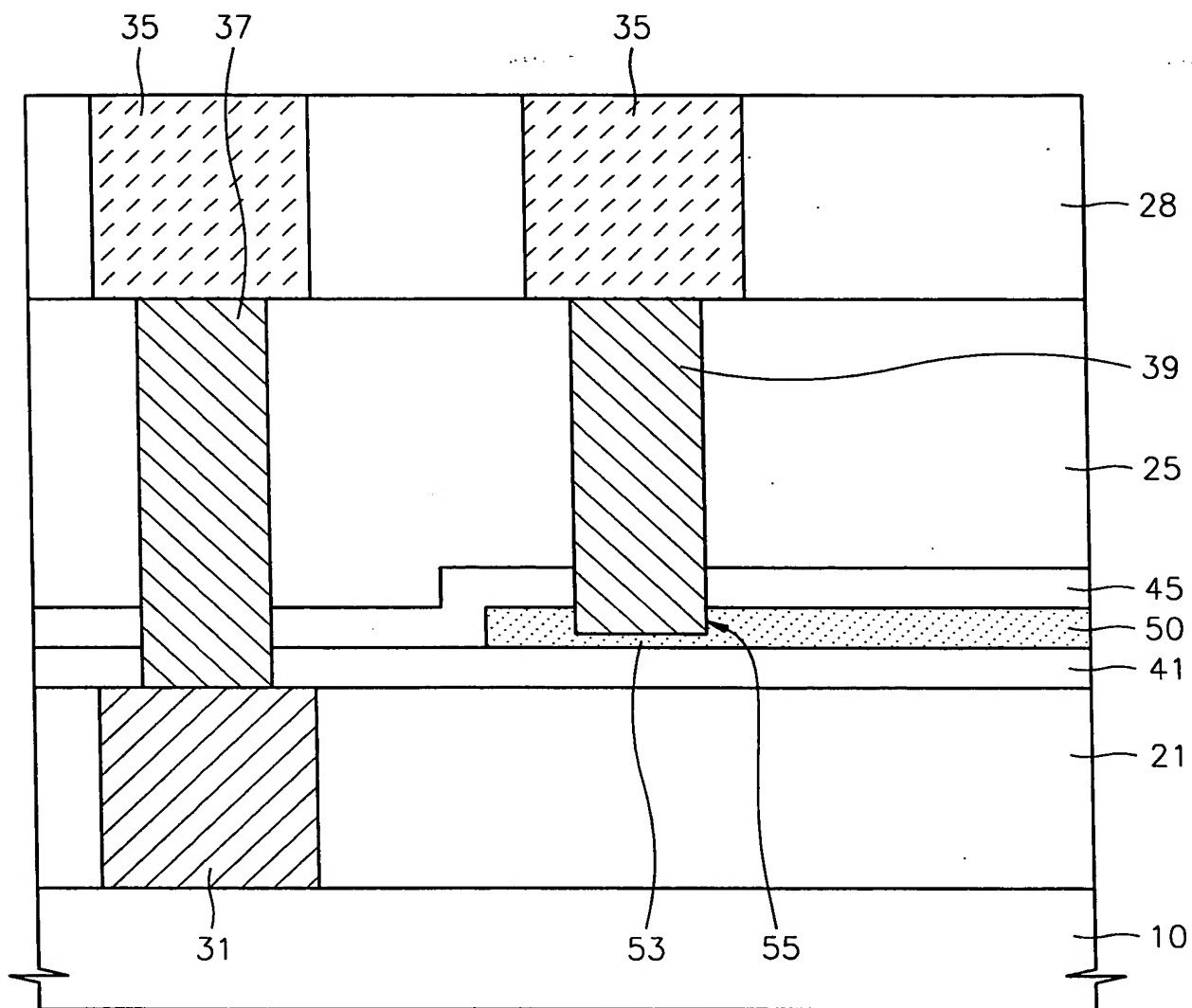


FIG. 5

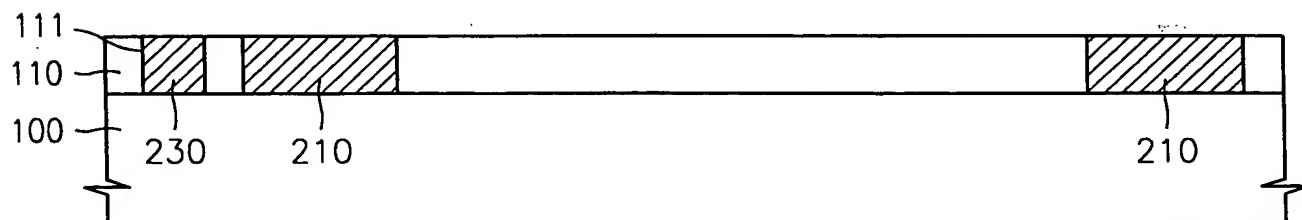


FIG. 6

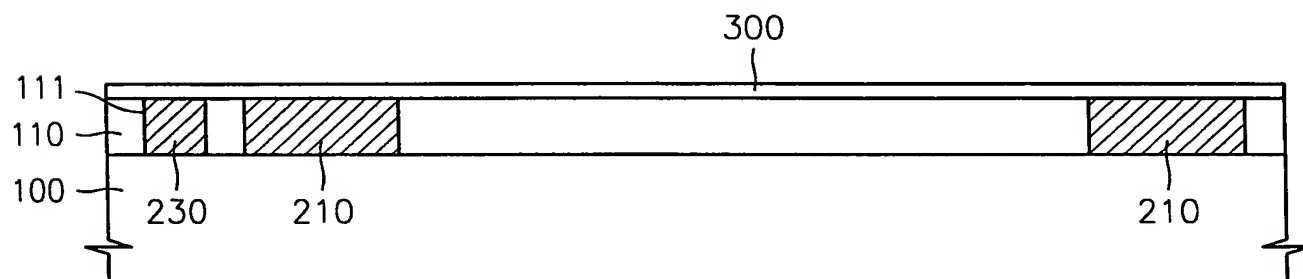


FIG. 7

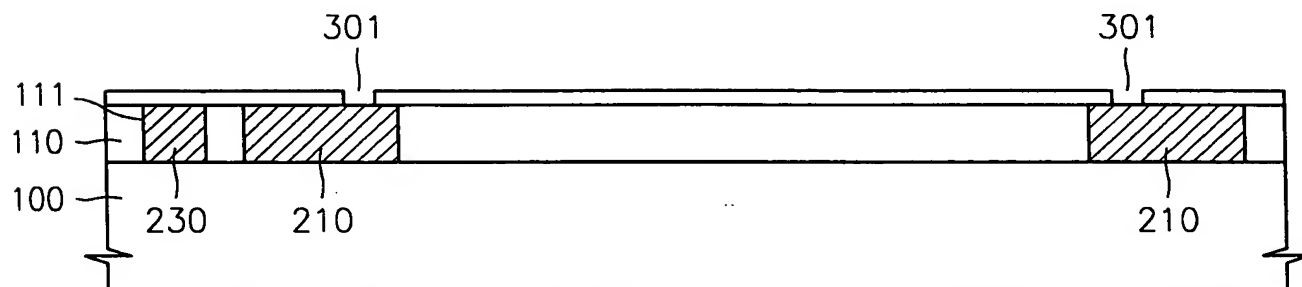


FIG. 8

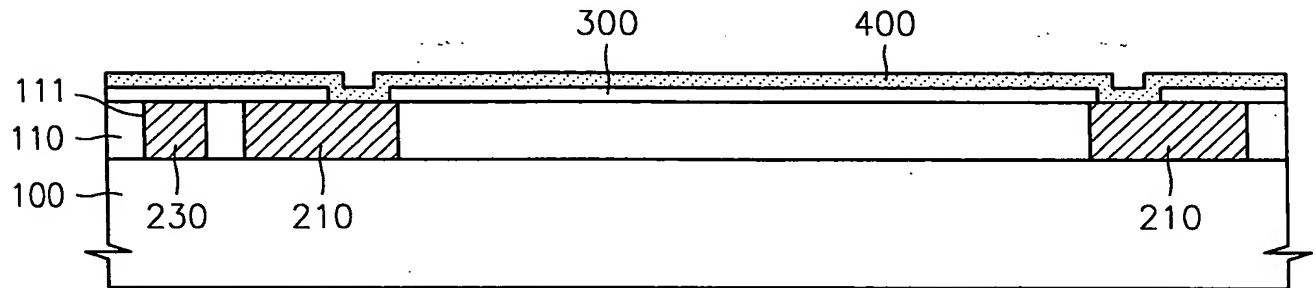


FIG. 9

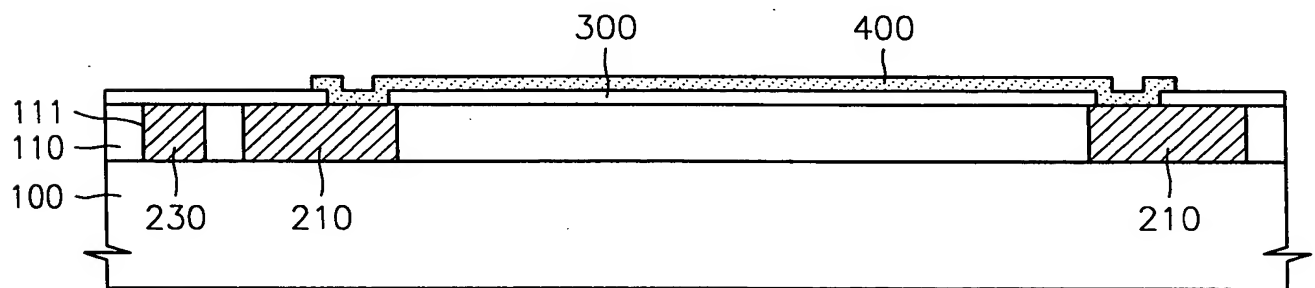


FIG. 10

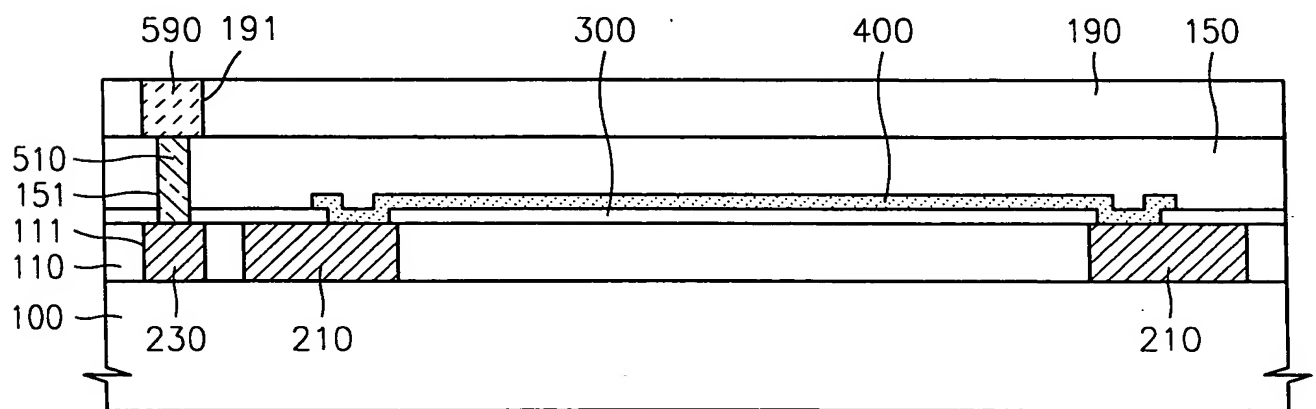


FIG. 11A

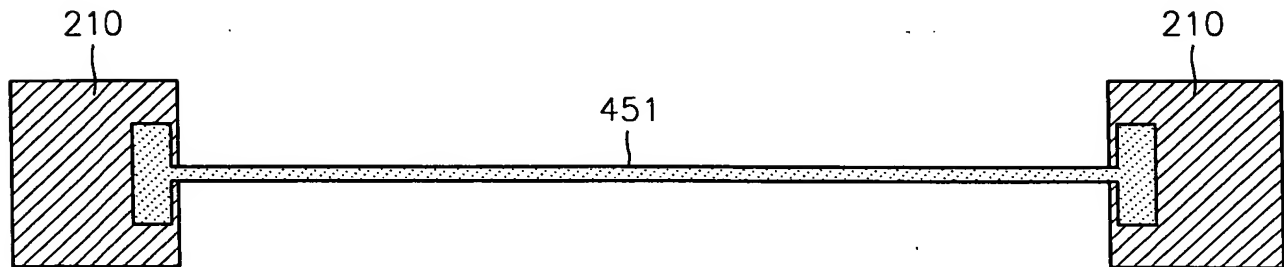


FIG. 11B

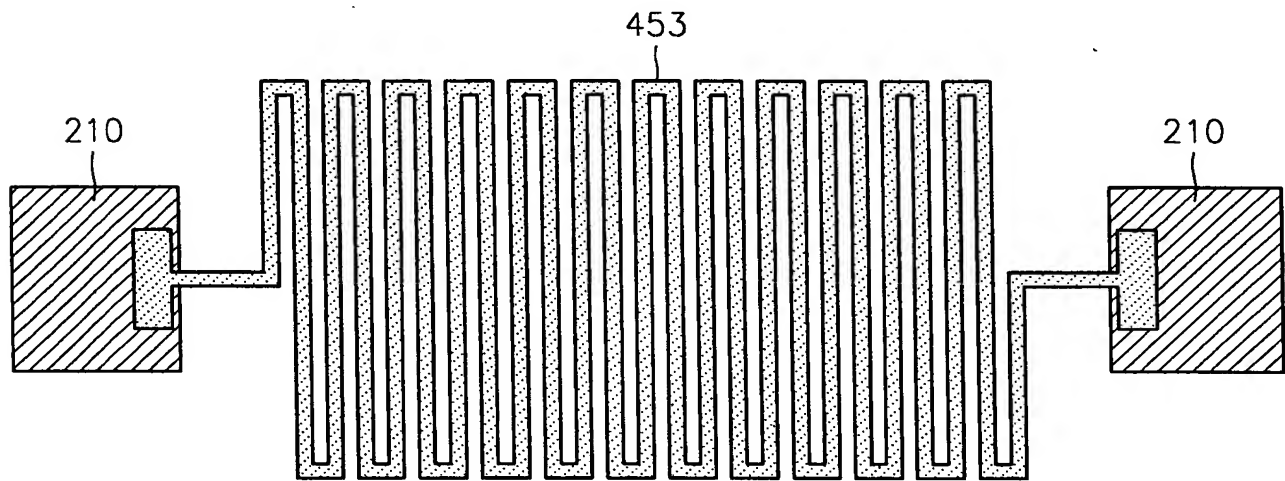


FIG. 12

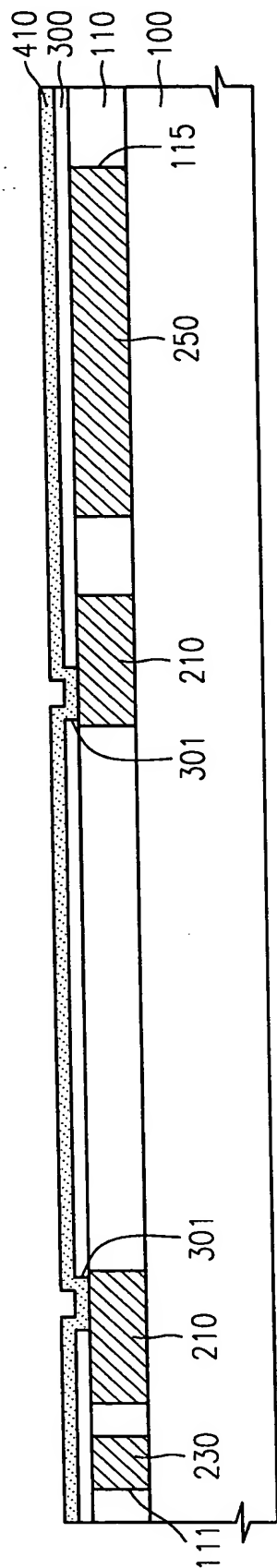
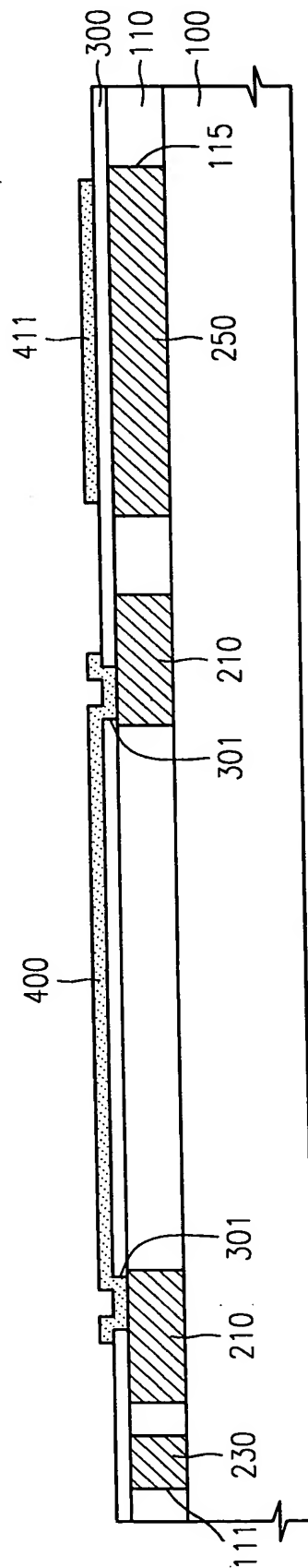


FIG. 13







[illegible]

This cross-sectional view shows a semiconductor device with a trench structure. The device includes a substrate 100 with a top layer 110. A trench 111 is formed in the substrate. A first layer 210 is deposited in the trench, and a second layer 230 is deposited on top of the first layer. A third layer 301 is deposited on top of the second layer. A fourth layer 400 is deposited on top of the third layer. A fifth layer 423 is deposited on top of the fourth layer. A sixth layer 421 is deposited on top of the fifth layer. A seventh layer 425 is deposited on top of the sixth layer. A eighth layer 300 is deposited on top of the seventh layer. The layers 210, 230, and 301 are shown with different hatching patterns to indicate they are different materials.

FIG. 18

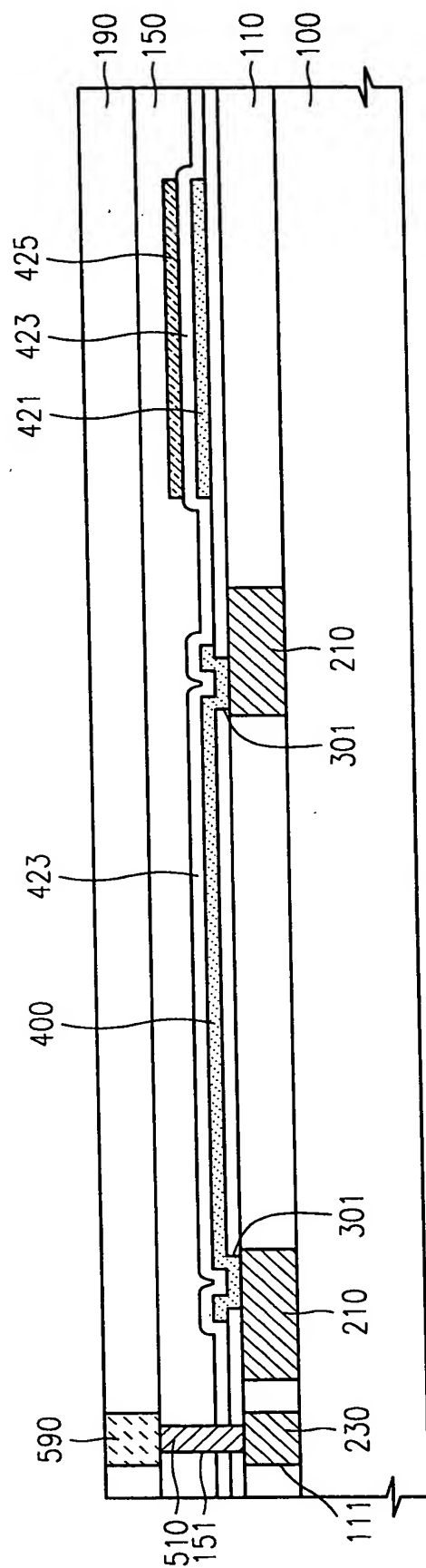


FIG. 19

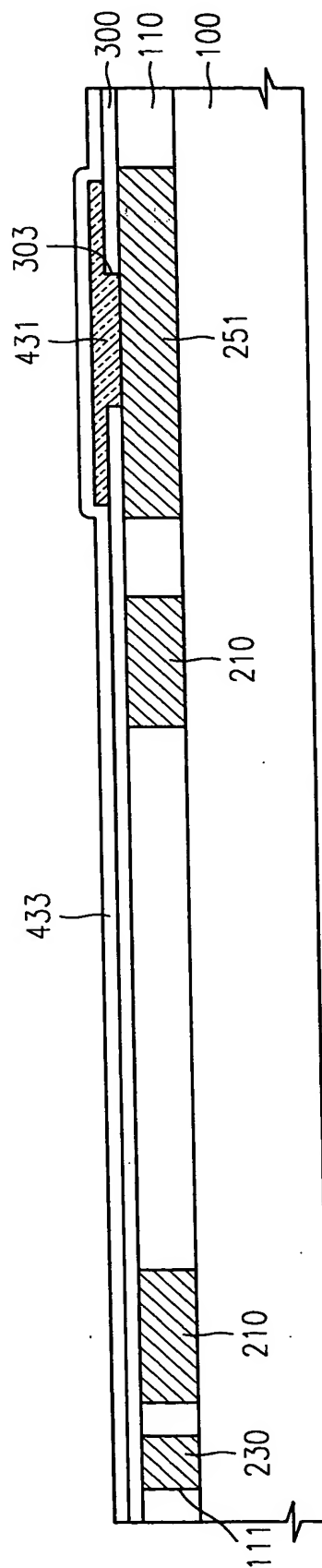


FIG. 20

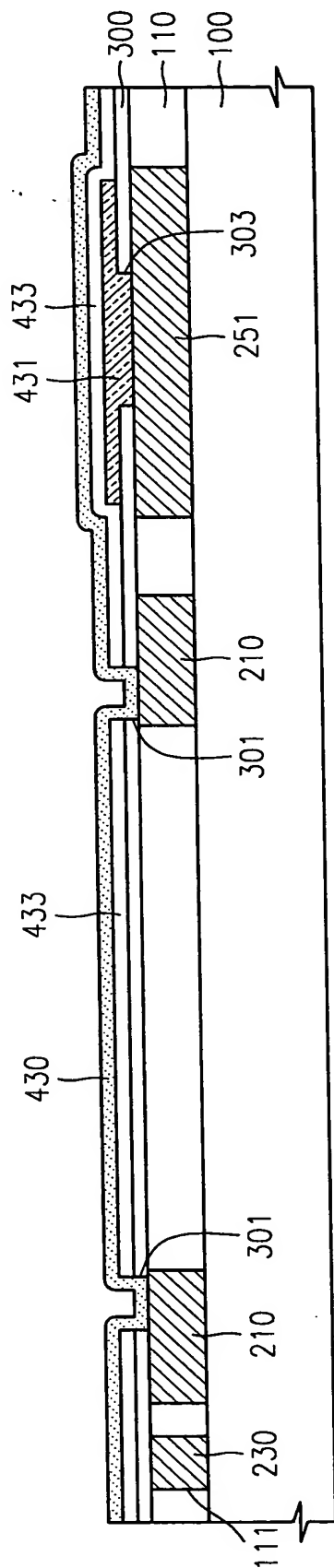
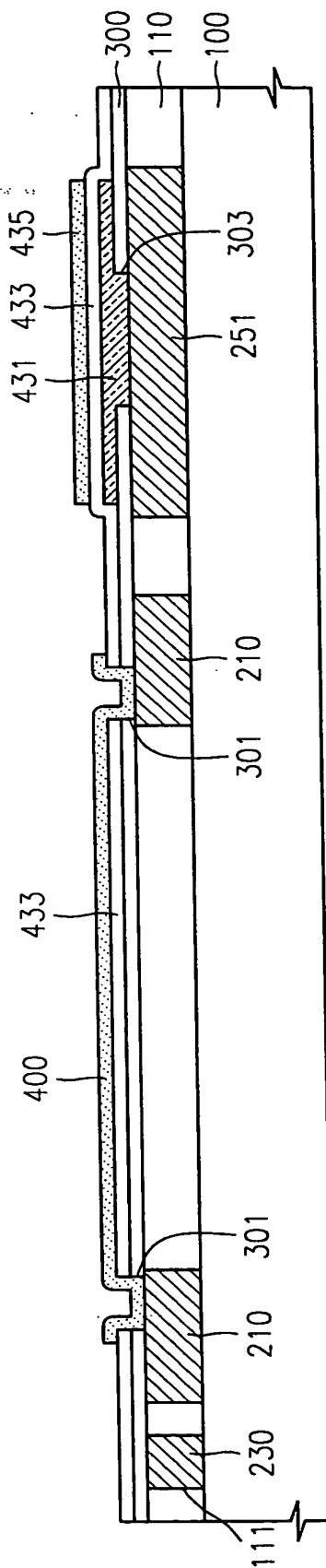


FIG. 21



[illegible]

This diagram shows a cross-sectional view of a multi-layered electronic device assembly. The assembly consists of several layers and components, labeled with reference numerals. At the top, there is a layer labeled 190, followed by a layer labeled 150. Below these is a layer labeled 300, which contains a central core labeled 110. The core 110 is surrounded by a material labeled 100. The assembly is further divided into sections labeled 431, 433, and 435. A layer labeled 590 is shown at the bottom left, and a layer labeled 510 is shown at the bottom right. A layer labeled 151 is also indicated. The assembly is shown in a perspective view, with a break line at the bottom indicating that the structure continues.

FIG. 24

